ICROCHIP TC4426/TC4427/TC4428

1.5A Dual High-Speed Power MOSFET Drivers

Features

- High Peak Output Current 1.5A
- Wide Input Supply Voltage Operating Range:
 - 4.5V to 18V
- High Capacitive Load Drive Capability 1000 pF in 25 ns (typ.)
- Short Delay Times 40 ns (typ.)
- · Matched Rise and Fall Times
- Low Supply Current:
 - With Logic '1' Input 4 mA
 - With Logic '0' Input 400 μA
- Low Output Impedance 7Ω
- Latch-Up Protected: Will Withstand 0.5A Reverse Current
- Input Will Withstand Negative Inputs Up to 5V
- ESD Protected 4 kV
- Pin-compatible with the TC426/TC427/TC428
- Space-saving 8-Pin MSOP and 8-Pin 6x5 DFN Packages

Applications

- Switch Mode Power Supplies
- Line Drivers
- Pulse Transformer Drive

General Description

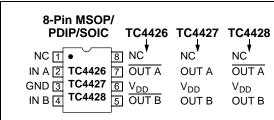
The TC4426/TC4427/TC4428 are improved versions of the earlier TC426/TC427/TC428 family of MOSFET drivers. The TC4426/TC4427/TC4428 devices have matched rise and fall times when charging and discharging the gate of a MOSFET.

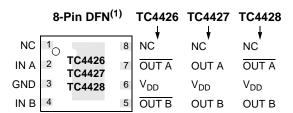
These devices are highly latch-up resistant under any conditions within their power and voltage ratings. They are not subject to damage when up to 5V of noise spiking (of either polarity) occurs on the ground pin. They can accept, without damage or logic upset, up to 500 mA of reverse current (of either polarity) being forced back into their outputs. All terminals are fully protected against Electrostatic Discharge (ESD) up to 4 kV

The TC4426/TC4427/TC4428 MOSFET drivers can easily charge/discharge 1000 pF gate capacitances in under 30 ns. These device provide low enough impedances in both the on and off states to ensure the MOSFET's intended state will not be affected, even by large transients.

Other compatible drivers are the TC4426A/TC4427A/TC4428A family of devices. The TC4426A/TC4427A/TC4428A devices have matched leading and falling edge input-to-output delay times, in addition to the matched rise and fall times of the TC4426/TC4427/TC4428 devices.

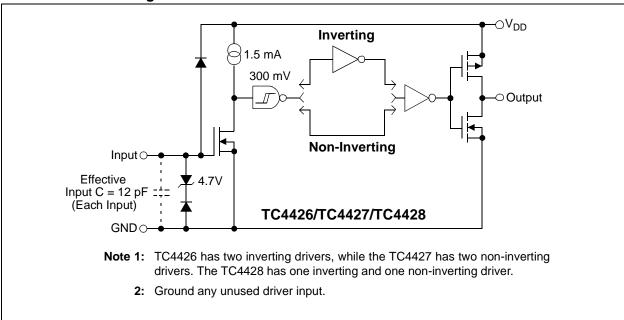
Package Types





Note 1: Exposed pad of the DFN package is electrically isolated.

Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

| Supply Voltage+22V |
|---|
| Input Voltage, IN A or IN B |
| (V _{DD} + 0.3V) to (GND – 5V) |
| Package Power Dissipation (T _A ≤ 70°C) |
| DFN Note 3 |
| MSOP340 mW |
| PDIP |
| SOIC470 mW |
| Storage Temperature Range65°C to +150°C |
| Maximum Junction Temperature+150°C |

† Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

PIN FUNCTION TABLE

| Name | Function | | | | |
|----------|---------------|--|--|--|--|
| NC | No Connection | | | | |
| IN A | Input A | | | | |
| GND | Ground | | | | |
| IN B | Input B | | | | |
| OUT B | Output B | | | | |
| V_{DD} | Supply Input | | | | |
| OUT A | Output A | | | | |
| NC | No Connection | | | | |

DC CHARACTERISTICS

| Electrical Specifications: Unless otherwise noted, $T_A = +25^{\circ}C$ with 4.5V $\leq V_{DD} \leq 18V$. | | | | | | | |
|---|------------------|-------------------------|-------|-------|-------|---|--|
| Parameters | Sym | Min | Тур | Max | Units | Conditions | |
| Input | | | | | | | |
| Logic '1', High Input Voltage | V _{IH} | 2.4 | _ | _ | V | Note 2 | |
| Logic '0', Low Input Voltage | V_{IL} | _ | _ | 0.8 | V | | |
| Input Current | I _{IN} | -1.0 | _ | +1.0 | μA | $0V \le V_{IN} \le V_{DD}$ | |
| Output | | | | | | | |
| High Output Voltage | V _{OH} | V _{DD} – 0.025 | _ | _ | V | DC Test | |
| Low Output Voltage | V _{OL} | _ | _ | 0.025 | V | DC Test | |
| Output Resistance | R _O | _ | 7 | 10 | Ω | I _{OUT} = 10 mA, V _{DD} = 18V | |
| Peak Output Current | I _{PK} | _ | 1.5 | | Α | V _{DD} = 18V | |
| Latch-Up Protection | I _{REV} | _ | > 0.5 | _ | Α | Duty cycle ≤ 2%, t ≤ 300 µs | |
| Withstand Reverse Current | | | | | | V _{DD} = 18V | |
| Switching Time (Note 1) | | | | | | | |
| Rise Time | t _R | _ | 19 | 30 | ns | Figure 4-1 | |
| Fall Time | t _F | _ | 19 | 30 | ns | Figure 4-1 | |
| Delay Time | t _{D1} | _ | 20 | 30 | ns | Figure 4-1 | |
| Delay Time | t _{D2} | _ | 40 | 50 | ns | Figure 4-1 | |
| Power Supply | | | | | | | |
| Power Supply Current | I _S | _ | _ | 4.5 | mA | V _{IN} = 3V (Both inputs) | |
| | | _ | _ | 0.4 | | V _{IN} = 0V (Both inputs) | |

- Note 1: Switching times ensured by design.
 - 2: For V temperature range devices, the V_{IH} (Min) limit is 2.0V.
 - 3: Package power dissipation is dependent on the copper pad area on the PCB.

DC CHARACTERISTICS (OVER OPERATING TEMPERATURE RANGE)

| Electrical Specifications: Unless otherwise noted, over operating temperature range with $4.5V \le V_{DD} \le 18V$. | | | | | | | |
|---|------------------|-------------------------|------|------------|-------|--|--|
| Parameters | Sym | Min | Тур | Max | Units | Conditions | |
| Input | | | | | | | |
| Logic '1', High Input Voltage | V _{IH} | 2.4 | _ | _ | V | Note 2 | |
| Logic '0', Low Input Voltage | V_{IL} | _ | _ | 0.8 | V | | |
| Input Current | I _{IN} | -10 | _ | +10 | μA | $0V \le V_{IN} \le V_{DD}$ | |
| Output | | | | | | | |
| High Output Voltage | V _{OH} | V _{DD} – 0.025 | _ | _ | V | DC Test | |
| Low Output Voltage | V _{OL} | _ | | 0.025 | V | DC Test | |
| Output Resistance | R _O | _ | 9 | 12 | Ω | I _{OUT} = 10 mA, V _{DD} = 18V | |
| Peak Output Current | I _{PK} | _ | 1.5 | _ | Α | V _{DD} = 18V | |
| Latch-Up Protection Withstand Reverse Current | I _{REV} | _ | >0.5 | _ | Α | Duty cycle \leq 2%, t \leq 300 µs $V_{DD} = 18V$ | |
| Switching Time (Note 1) | | | | | | , == | |
| Rise Time | t _R | _ | _ | 40 | ns | Figure 4-1 | |
| Fall Time | t _F | _ | _ | 40 | ns | Figure 4-1 | |
| Delay Time | t _{D1} | _ | _ | 40 | ns | Figure 4-1 | |
| Delay Time | t _{D2} | _ | _ | 60 | ns | Figure 4-1 | |
| Power Supply | | | | | | | |
| Power Supply Current | I _S | _ | | 8.0 0.6 | mA | V _{IN} = 3V (Both inputs) V _{IN} = 0V (Both inputs) | |

Note 1: Switching times ensured by design.

2: For V temperature range devices, the V_{IH} (Min) limit is 2.0V.

TEMPERATURE CHARACTERISTICS

| Electrical Specifications: Unless otherwise noted, all parameters apply with $4.5V \le V_{DD} \le 18V$. | | | | | | | | |
|---|----------------|-----|------|------|-------|------------|--|--|
| Parameters | Sym | Min | Тур | Max | Units | Conditions | | |
| Temperature Ranges | | | | | | | | |
| Specified Temperature Range (C) | T _A | 0 | _ | +70 | °C | | | |
| Specified Temperature Range (E) | T _A | -40 | _ | +85 | °C | | | |
| Specified Temperature Range (V) | T _A | -40 | _ | +125 | °C | | | |
| Maximum Junction Temperature | TJ | _ | _ | +150 | °C | | | |
| Storage Temperature Range | T _A | -65 | _ | +150 | °C | | | |
| Package Thermal Resistances | | | | | | | | |
| Thermal Resistance, 8L-6x5 DFN | θ_{JA} | _ | 33.2 | _ | °C/W | | | |
| Thermal Resistance, 8L-MSOP | θ_{JA} | _ | 206 | _ | °C/W | | | |
| Thermal Resistance, 8L-PDIP | θ_{JA} | _ | 125 | _ | °C/W | | | |
| Thermal Resistance, 8L-SOIC | θ_{JA} | _ | 155 | _ | °C/W | | | |

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with $4.5V \le V_{DD} \le 18V$.

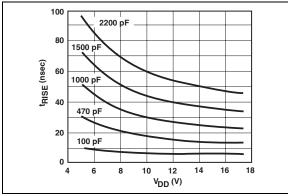
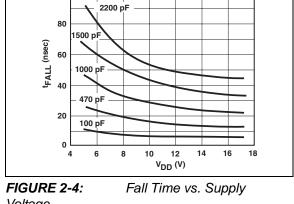


FIGURE 2-1: Rise Time vs. Supply Voltage.



Voltage.

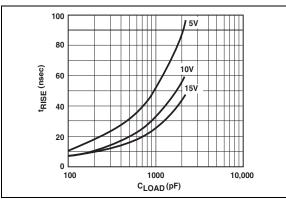


FIGURE 2-2: Rise Time vs. Capacitive Load.

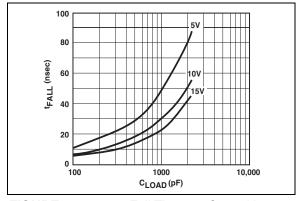
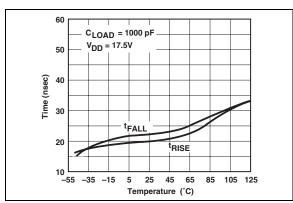


FIGURE 2-5: Fall Time vs. Capacitive Load.



Rise and Fall Times vs. FIGURE 2-3: Temperature.

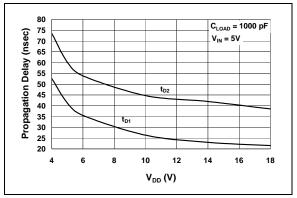


FIGURE 2-6: Propagation Delay Time vs. Supply Voltage.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with 4.5V $\leq V_{DD} \leq 18V$.

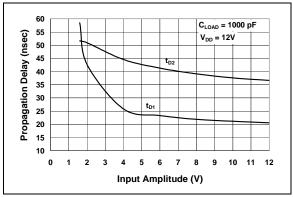


FIGURE 2-7: Propagation Delay Time vs. Input Amplitude.

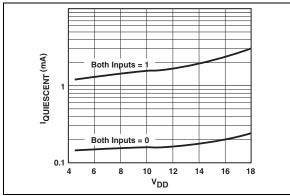


FIGURE 2-8: Supply Current vs. Supply Voltage.

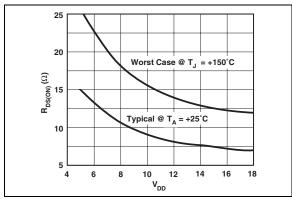


FIGURE 2-9: Output Resistance (R_{OH}) vs. Supply Voltage.

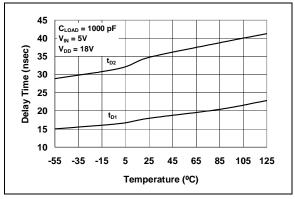


FIGURE 2-10: Propagation Delay Time vs. Temperature.

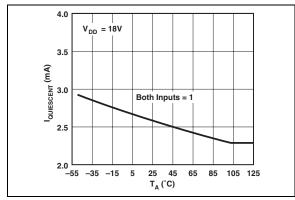


FIGURE 2-11: Supply Current vs. Temperature.

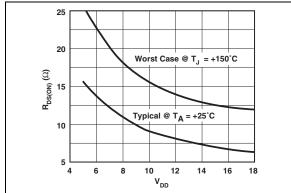


FIGURE 2-12: Output Resistance (R_{OL}) vs. Supply Voltage.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with 4.5V $\leq V_{DD} \leq 18V$.

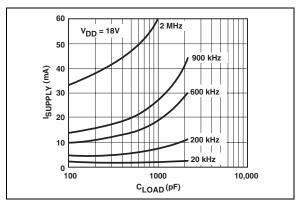


FIGURE 2-13: Supply Current vs. Capacitive Load.

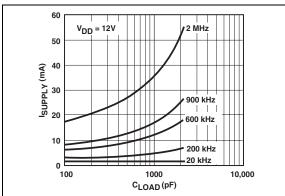


FIGURE 2-14: Supply Current vs. Capacitive Load.

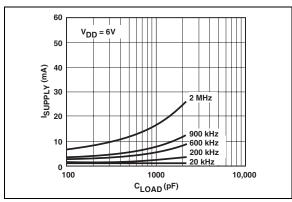


FIGURE 2-15: Supply Current vs. Capacitive Load.

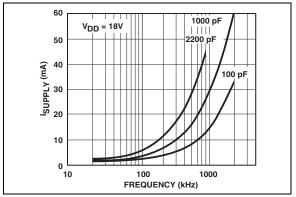


FIGURE 2-16: Supply Current vs. Frequency.

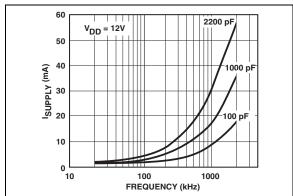


FIGURE 2-17: Supply Current vs. Frequency.

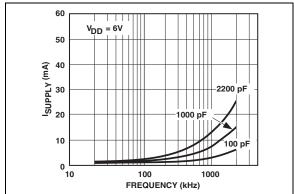
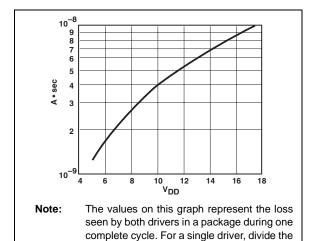


FIGURE 2-18: Supply Current vs. Frequency.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with 4.5V $\leq V_{DD} \leq 18V$.



stated values by 2. For a single transition of a single driver, divide the stated value by 4.

FIGURE 2-19: Crossover Energy vs. Supply Voltage.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE (1)

| 8-Pin PDIP/ MSOP/SOIC | 8-Pin DFN | Symbol | Description |
|--------------------------|--------------|----------|-------------------|
| 1 | 1 | NC | No connection |
| 2 | 2 | IN A | Input A |
| 3 | 3 | GND | Ground |
| 4 | 4 | IN B | Input B |
| 5 | 5 | OUT B | Output B |
| 6 | 6 | V_{DD} | Supply input |
| 7 | 7 | OUT A | Output A |
| 8 | 8 | NC | No connection |
| _ | PAD | NC | Exposed Metal Pad |

Note 1: Duplicate pins must be connected for proper operation.

3.1 Inputs A and B

MOSFET driver inputs A and B are high-impedance, TTL/CMOS compatible inputs. These inputs also have 300 mV of hysteresis between the high and low thresholds that prevents output glitching even when the rise and fall time of the input signal is very slow.

3.2 Ground (GND)

Ground is the device return pin. The ground pin(s) should have a low-impedance connection to the bias supply source return. High peak currents will flow out the ground pin(s) when the capacitive load is being discharged.

3.3 Output A and B

MOSFET driver outputs A and B are low-impedance, CMOS push-pull style outputs. The pull-down and pull-up devices are of equal strength, making the rise and fall times equivalent.

3.4 Supply Input (V_{DD})

The V_{DD} input is the bias supply for the MOSFET driver and is rated for 4.5V to 18V with respect to the ground pin. The V_{DD} input should be bypassed with local ceramic capacitors. The value of these capacitors should be chosen based on the capacitive load that is being driven. A value of 1.0 μ F is suggested.

3.5 Exposed Metal Pad

The exposed metal pad of the 6x5 DFN package is not internally connected to any potential. Therefore, this pad can be connected to a ground plane or other copper plane on a printed circuit board, to aid in heat removal from the package.

4.0 APPLICATIONS INFORMATION

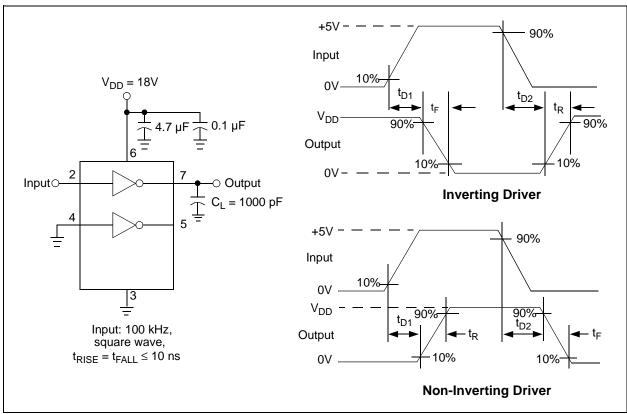


FIGURE 4-1: Switching Time Test Circuit.

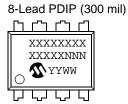
5.0 PACKAGING INFORMATION

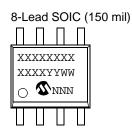
5.1 Package Marking Information





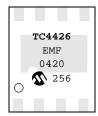




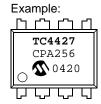


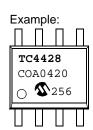
for customer specific information.







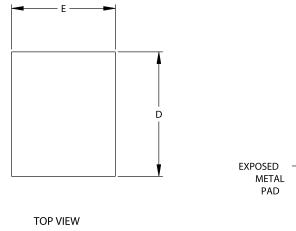


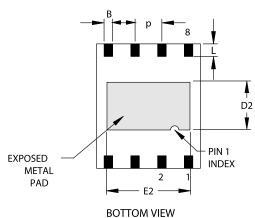


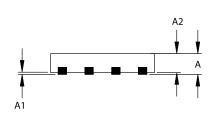
| Legend: | XXX Y YY | Customer specific information* Year code (last digit of calendar year) Year code (last 2 digits of calendar year) |
|---------|----------------|--|
| | WW NNN | Week code (week of January 1 is week '01') Alphanumeric traceability code |
| | | nt the full Microchip part number cannot be marked on one line, it will over to the next line thus limiting the number of available characters |

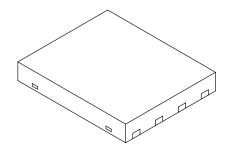
* Standard device marking consists of Microchip part number, year code, week code, and traceability code.

8-Lead Plastic Dual Flat No Lead Package (MF) 6x5 mm Body (DFN-S) - Saw Singulated









| | Units | | INCHES | | | ILLIMETERS* | |
|--------------------|-------|------|----------|------|------|-------------|------|
| Dimension Lim | its | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | р | | .050 BSC | | | 1.27 BSC | |
| Overall Height | Α | .033 | .035 | .037 | 0.85 | 0.90 | 0.95 |
| Package Thickness | A2 | .031 | .035 | .037 | 0.80 | 0.89 | 0.95 |
| Standoff | A1 | .000 | .0004 | .002 | 0.00 | 0.01 | 0.05 |
| Base Thickness | A3 | .007 | .008 | .009 | 0.17 | 0.20 | 0.23 |
| Overall Length | Е | .195 | .197 | .199 | 4.95 | 5.00 | 5.05 |
| Exposed Pad Length | E2 | .152 | .157 | .163 | 3.85 | 4.00 | 4.15 |
| Overall Width | D | .234 | .236 | .238 | 5.95 | 6.00 | 6.05 |
| Exposed Pad Width | D2 | .089 | .091 | .093 | 2.25 | 2.30 | 2.35 |
| Lead Width | В | .014 | .016 | .019 | 0.35 | 0.40 | 0.47 |
| Lead Length | L | .024 | | .026 | 0.60 | | 0.65 |

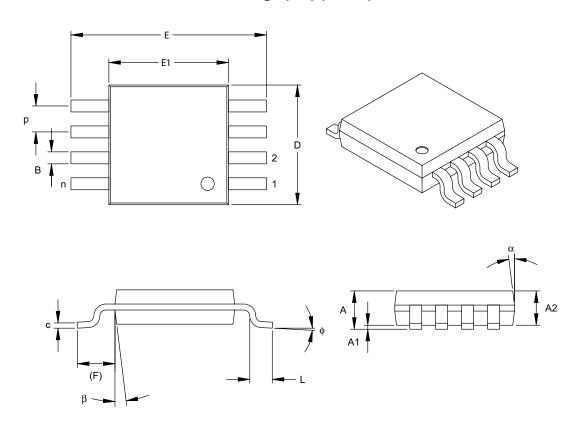
Notes:

JEDEC equivalent: MO-220

Drawing No. C04-122

Revised 11/3/03

8-Lead Plastic Micro Small Outline Package (MS) (MSOP)



| | Units | | INCHES | | М | ILLIMETERS | * |
|--------------------------|-------|------|-----------|------|------|------------|------|
| Dimension Lim | its | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | р | | .026 BSC | | | 0.65 BSC | |
| Overall Height | Α | - | - | .043 | - | - | 1.10 |
| Molded Package Thickness | A2 | .030 | .033 | .037 | 0.75 | 0.85 | 0.95 |
| Standoff | A1 | .000 | - | .006 | 0.00 | - | 0.15 |
| Overall Width | E | | .193 TYP. | | | 4.90 BSC | |
| Molded Package Width | E1 | | .118 BSC | | | 3.00 BSC | |
| Overall Length | D | | .118 BSC | | | 3.00 BSC | |
| Foot Length | L | .016 | .024 | .031 | 0.40 | 0.60 | 0.80 |
| Footprint (Reference) | F | | .037 REF | | | 0.95 REF | |
| Foot Angle | ф | 0° | - | 8° | 0° | - | 8° |
| Lead Thickness | С | .003 | .006 | .009 | 0.08 | - | 0.23 |
| Lead Width | В | .009 | .012 | .016 | 0.22 | - | 0.40 |
| Mold Draft Angle Top | α | 5° | - | 15° | 5° | - | 15° |
| Mold Draft Angle Bottom | β | 5° | - | 15° | 5° | - | 15° |

^{*}Controlling Parameter

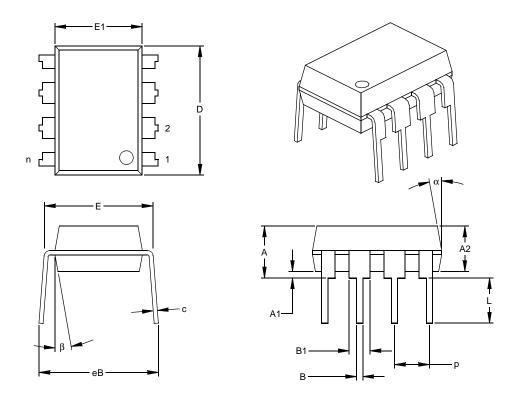
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

8-Lead Plastic Dual In-line (P) - 300 mil (PDIP)



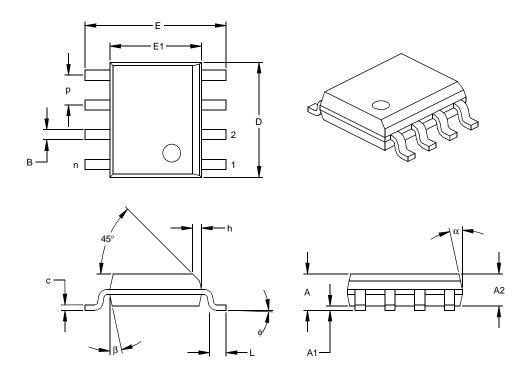
| | | INCHES* | | MILLIMETERS | | | |
|----------------------------|--------|---------|------|-------------|------|------|-------|
| Dimension | Limits | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | р | | .100 | | | 2.54 | |
| Top to Seating Plane | Α | .140 | .155 | .170 | 3.56 | 3.94 | 4.32 |
| Molded Package Thickness | A2 | .115 | .130 | .145 | 2.92 | 3.30 | 3.68 |
| Base to Seating Plane | A1 | .015 | | | 0.38 | | |
| Shoulder to Shoulder Width | Е | .300 | .313 | .325 | 7.62 | 7.94 | 8.26 |
| Molded Package Width | E1 | .240 | .250 | .260 | 6.10 | 6.35 | 6.60 |
| Overall Length | D | .360 | .373 | .385 | 9.14 | 9.46 | 9.78 |
| Tip to Seating Plane | L | .125 | .130 | .135 | 3.18 | 3.30 | 3.43 |
| Lead Thickness | С | .008 | .012 | .015 | 0.20 | 0.29 | 0.38 |
| Upper Lead Width | B1 | .045 | .058 | .070 | 1.14 | 1.46 | 1.78 |
| Lower Lead Width | В | .014 | .018 | .022 | 0.36 | 0.46 | 0.56 |
| Overall Row Spacing § | eВ | .310 | .370 | .430 | 7.87 | 9.40 | 10.92 |
| Mold Draft Angle Top | α | 5 | 10 | 15 | 5 | 10 | 15 |
| Mold Draft Angle Bottom | β | 5 | 10 | 15 | 5 | 10 | 15 |

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

.010" (0.254mm) per side. JEDEC Equivalent: MS-001 Drawing No. C04-018

^{*} Controlling Parameter § Significant Characteristic

8-Lead Plastic Small Outline (SN) - Narrow, 150 mil (SOIC)



| | | INCHES* | | MILLIMETERS | | | |
|--------------------------|--------|---------|------|-------------|------|------|------|
| Dimension | Limits | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | р | | .050 | | | 1.27 | |
| Overall Height | Α | .053 | .061 | .069 | 1.35 | 1.55 | 1.75 |
| Molded Package Thickness | A2 | .052 | .056 | .061 | 1.32 | 1.42 | 1.55 |
| Standoff § | A1 | .004 | .007 | .010 | 0.10 | 0.18 | 0.25 |
| Overall Width | Е | .228 | .237 | .244 | 5.79 | 6.02 | 6.20 |
| Molded Package Width | E1 | .146 | .154 | .157 | 3.71 | 3.91 | 3.99 |
| Overall Length | D | .189 | .193 | .197 | 4.80 | 4.90 | 5.00 |
| Chamfer Distance | h | .010 | .015 | .020 | 0.25 | 0.38 | 0.51 |
| Foot Length | L | .019 | .025 | .030 | 0.48 | 0.62 | 0.76 |
| Foot Angle | ф | 0 | 4 | 8 | 0 | 4 | 8 |
| Lead Thickness | С | .008 | .009 | .010 | 0.20 | 0.23 | 0.25 |
| Lead Width | В | .013 | .017 | .020 | 0.33 | 0.42 | 0.51 |
| Mold Draft Angle Top | α | 0 | 12 | 15 | 0 | 12 | 15 |
| Mold Draft Angle Bottom | β | 0 | 12 | 15 | 0 | 12 | 15 |

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

.010" (0.254mm) per side. JEDEC Equivalent: MS-012 Drawing No. C04-057

^{*} Controlling Parameter § Significant Characteristic

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| PART NO. X | <u>xx xxx </u> | Examples: |
|---------------------|---|--|
| Device Tempe Ran | erature Package Tape & Reel PB Free nge | a) TC4426COA: 1.5A Dual Inverting MOSFET driver, 0°C to +70°C SOIC package. |
| Device: | TC4426: 1.5A Dual MOSFET Driver, Inverting TC4427: 1.5A Dual MOSFET Driver, Non-Inverting TC4428: 1.5A Dual MOSFET Driver, Complementary | b) TC4426EUA: 1.5A Dual Inverting MOSFET driver, -40°C to +85°C. MSOP package. |
| Temperature Range: | C = 0°C to +70°C (PDIP and SOIC only) E = -40°C to +85°C V = -40°C to +125°C | c) TC4426EMF: 1.5A Dual Inverting MOSFET driver, -40°C to +85°C, DFN package. |
| Package: | MF = Dual, Flat, No-Lead (6X5 mm Body), 8-lead MF713 = Dual, Flat, No-Lead (6X5 mm Body), 8-lead (Tape and Reel) OA = Plastic SOIC, (150 mil Body), 8-lead OA713 = Plastic SOIC, (150 mil Body), 8-lead | a) TC4427CPA: 1.5A Dual Non-Inverting MOSFET driver, 0°C to +70°C PDIP package. |
| | (Tape and Reel) PA = Plastic DIP (300 mil Body), 8-lead UA = Plastic Micro Small Outline (MSOP), 8-lead UA713 = Plastic Micro Small Outline (MSOP), 8-lead (Tape and Reel) | b) TC4427EPA: 1.5A Dual Non-Inverting MOSFET driver, -40°C to +85°C PDIP package. |
| | | a) TC4428COA713:1.5A Dual Complementary MOSFET driver, |
| PB Free: | G = Lead-Free device * = Blank | 0°C to +70°C, SOIC package, Tape and Reel. |
| | * Available on selected packages. Contact your local sales representative for availability. | b) TC4428EMF: 1.5A Dual Complementary, MOSFET driver, -40°C to +85°C DFN package. |

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